

DOCKET NO: 0039-7632-0X

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF:
Hiroyuki YANO, et al.

PATENT NO.: 6,740,590

: EXAMINER: Duy V. Nguyen DEO

ISSUED: May 25, 2004

:GROUP: 1765

FOR: AQUEOUS DISPERSION, AQUEOUS DISPERSION FOR CHEMICAL
MECHANICAL POLISHING USED FOR MANUFACTURE OF SEMICONDUCTOR
DEVICES, METHOD FOR MANUFACTURE OF SEMICONDUCTOR DEVICES,
AND METHOD FOR FORMATION OF EMBEDDED WIRING.

REQUEST FOR CORRECTED CERTIFICATE OF CORRECTION

HONORABLE COMMISSIONER OF PATENTS & TRADEMARKS
WASHINGTON, DC

SIR:

Attached is a copy of a Certificate of Correction issued in the above-identified Patent. It has been marked-up to indicate errors made by the Patent Office. Also attached is a copy of our Form PTO-1050 as filed on June 10, 2004.

Please issue a correct Certificate of Correction to "supercede" the incorrect one issued on February 15, 2005.

In light of the fact that the errors are the fault of the Patent Office, no fees are required.

Respectfully submitted,

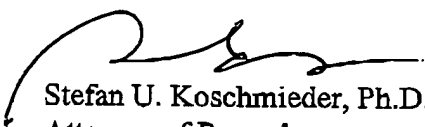
OBLON, SPIVAK, McCLELLAND,
MAIER & NEUSTADT, P.C.
Norman F. Oblon

Customer Number

22850

(703)413-3000

Fax: (703)413-2220



Stefan U. Koschmieder, Ph.D.
Attorney of Record
Registration Number: 50,238

Roland E. Martin
Registration No. 48,082

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : 6,740,590
DATED: May 25, 2004
INVENTOR(S): Yano et al.

It is certified that an error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

On the title page, Item (54), and in Column 1 the title information should read:

-- (54) **AQUEOUS DISPERSION, AQUEOUS DISPERSION FOR CHEMICAL MECHANICAL POLISHING USED FOR MANUFACTURE OF SEMICONDUCTOR DEVICES, METHOD FOR MANUFACTURE OF SEMICONDUCTOR DEVICES, AND METHOD FOR FORMATION OF EMBEDDED WIRING --**

Mailing address of sender:

Patent No. 6,740,590

Customer Number

22850

No. of add'l copies
@ .30 per page

Tel. (703) 413-3000
Fax. (703) 413-2220
(OSM/N 03/02)



UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : 6,740,590 B1
DATED : May 25, 2004
INVENTOR(S) : Yano et al.

Page 1 of 1

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Title page, Item [54] and Column 1, lines 1-5.

Title, should read:

**– AQUEOUS DISPERSION, AQUEOUS DISPERSION FOR CHEMICAL
MECHANICAL POLISHING USED FOR MANUFACTURE OF
SEMICONDUCTOR DEVICES, METHOD FOR MANUFACTURE OF
SEMICONDUCTOR DEVICES, AND METHOD FOR FORMATION OF
EMBEDDED WIRING –**

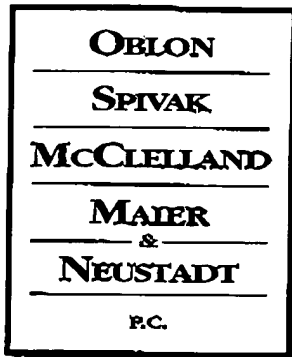
Signed and Sealed this

Fifteenth Day of February, 2005



JON W. DUDAS

Director of the United States Patent and Trademark Office



ATTORNEYS AT LAW

1840 DUKE STREET
ALEXANDRIA, VIRGINIA 22314
USA(703) 413-3000
(703) 413-2220 FACSIMILE

OBLONPAT@OBLON.COM

PATENT, TRADEMARK AND COPYRIGHT LAW
AND RELATED FEDERAL AND ITC LITIGATION

WWW.OBLON.COM

FACSIMILE

PLEASE CALL US AT (703) 413-3000 IF THE MESSAGE YOU RECEIVE IS INCOMPLETE OR NOT LEGIBLE

TO	Cecelia Newman	March 14, 2004
NAME	U.S.P.T.O.	DATE
COMPANY/FIRM		703-308-6672
NUMBER OF PAGES INCLUDING COVER:	4	FAX #
		CONFIRM FAX: <input type="checkbox"/> YES <input checked="" type="checkbox"/> NO
FROM	Mehreen Zehra	0039-7632-0X
NAME	703-412-6013	OUR REFERENCE
DIRECT PHONE #		6,740,590
		YOUR REFERENCE

MESSAGE

Please see the attached Request for Corrected Certificate of Correction.

Unless otherwise indicated or obvious from the nature of the transmittal, the information contained in this facsimile message is attorney privileged and confidential information intended for the use of the individual or entity named above. If the reader of this message is not the intended recipient or the employee or agent responsible to deliver it to the intended recipient, you are hereby notified that any dissemination, distribution or copying of this communication is strictly prohibited. If you have received this communication in error or are not sure whether it is privileged, please immediately notify us by telephone and return the original message to us at the above address via the U.S. Postal Service at our Expense. Thank You.